

Internet Address: www.emersoncuming.com

TYPI CAL	PROPERTI ES	TEST METHOD	DESCRI PTI ON
	Vi scosi ty @25° C:	22, 000 cps	PT- 42
	Filler:	Sil ver	
	Wbr k Li fe @25° C:	2 weeks	PT- 54
	Cure Condi ti on:	1 hour @150° C	
	Cure Opti on:	2 hour s @125° C	PT- 46
	Di e Shear St rengt h (80 ml ² l C) @ 25° C:	6600 psi	
	Vol ume Resi sti vi ty:	0. 0001 ohm cm	PT- 46
	I oni c Dat a		
	Chl ori de:	50 ppm	CT- 13
	Sodi um	10 ppm	
	Pot assi um	5 ppm	
	Water Extract Conducti vi ty:	13 µmhos / cm	CT- 6
	pH:	4. 5	
	Gl ass Transi ti on Temperat ure (Tg):	103° C	MT- 9
	Coef fi ci ent of Ther mal Expansi on (TMA)		MT- 9
	Bel ow Tg:	50 ppm / ° C	
	Above Tg:	200 ppm / ° C	
	Wei ght Loss (TGA) @300° C:	0. 16%	PT- 20
	Ther mal Conducti vi ty @121° C:	3. 60 W m ² K	PT- 40
	St or age Li fe		PT- 13
	@ 5° C:	3 mont hs	
	@- 10° C:	6 mont hs	
	@- 40° C:	1 year	

ABLEBOND 84-1LMIT1 hybrid chip adhesive is silver filled and electrically conductive. It exhibits an exceptional thermal conductivity of 3.60 W m² K.

This solvent-free adhesive is a lower viscosity version of ABLEBOND 84-1LMIT1 adhesive. It is designed for screen printing using 325 mesh.

ABLEBOND 84-1LMIT1 adhesive meets the requirements of ML-STD-883C, Method 5011.

The figures shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

INSTRUCTIONS

Apply adhesive as required. Assemble bonds. Cure at the recommended cure schedule(s).

AVAILABILITY

ABLEBOND84- 1LM T1 adhesive is available in a variety of package sizes, ranging from 1cc to 1 pound. This material may be purchased with M L- STD- 883, Method 5011 certification at an additional charge.

STORAGE

ABLEBOND84- 1LM T1 adhesive may be stored up to 3 months at 5°C (standard refrigerator temperature), 6 months at -10°C, or 1 year at -40°C.

HEALTH AND SAFETY

CAUTION This product may cause skin irritation in sensitive persons. Avoid skin contact. If contact does occur, wash area immediately with soap and water. Please refer to Material Safety Data Sheet (OSHA) for more details.

"In the event this product is intended by you for use in implantation in the human body, you are hereby advised that National Starch (or Emerson & Cuming) has not performed clinical testing of these materials for implantation in the human body nor has National Starch (Emerson & Cuming) sought, nor received, approval from the FDA for the use of these material in implantation in the human body. It is YOUR responsibility, as a manufacturer of any such device, to ensure that all materials and processes relating to the manufacture of any medical device fully comply with all applicable federal, state and local laws, rules, regulations and requirements as well as any such laws, rules, regulations, directives or other orders of any foreign country where such product is sold. If you have not undertaken the necessary investigations to ensure compliance you are advised NOT TO USE this product in the manufacture of any device which is to be implanted in the human body. No representative of ours has any authority to change the foregoing provisions."

■ Underfills Solder Alternatives C.O.B. Materials
 Film Adhesives Thermal Interfaces ■



■ Encapsulants Coatings Adhesives
 Electrically Conductive Coatings and Adhesives ■

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